LPKF

OCTOBER 2026

INVESTOR PRESENTATION:

ADVANCED PACKAGING SOLUTIONS FOR AI GROWTH

Dr. Klaus Fiedler, CEO | Peter Mümmler, CFO

THE MANAGEMENT BOARD

Dr. Klaus Fiedler

Management Board member since January 2022; contract extended early, appointed until 31 December 2028

Responsible for Strategy, Sales & Marketing, HR, Production, Research & Development, Innovation and Investor Relations

Background

- **SCHOTT AG – Vice President, Head of Corporate New Ventures, Mainz (2017-2021)**
- **Knowles Electronics, China – VP Product Management (2015-2017); previously Senior Director Business Segment and Director R&D / Program Management APAC (2011-2015)**
- **NXP Semiconductors – Director Product Line Microphones, Vienna (2006-2011)**
- **Philips Research Laboratories – Senior Scientist, Aachen (2001-2006)**

Peter Mümmler

Management Board member since April 2025; appointed until March 2028

Responsible for Finance, Controlling, Digital & IT, Purchasing and Legal & Compliance

Background

- **Kiepe Electric, Düsseldorf – Managing Director / CFO, interim (2024-2025)**
- **Alstom Transportation – VP Finance DACH and Chairman, Alstom Germany (2021-2024); VP Finance Europe, Paris (2020-2021)**
- **Siemens / Siemens Mobility – Senior finance roles in Germany, USA and China (1994-2020)**

FIVE THINGS TO REMEMBER ABOUT LPKF

A proven suppler of production laser systems for 50 years – **now essential to AI advanced packaging**

01
PROVEN SUPPLIER WITH LEADING MARKET POSITIONS

Fifty years of production systems;
#1 in three of its four markets, installed base in 60+ countries

50

years supplying production systems

02
AI ADVANCED PACKAGING IS MOVING TO GLASS

Organic substrates are at their limits on size, speed and cost – glass answers all three

2027

ramp-up year begins

03
ACTIVE ACROSS ALL GLASS APPLICATIONS FOR AI

Strongly positioned in core substrates & interposers;
Sampling phase for in-package liquid cooling and co-packaged optics

EUR 1.7 billion

2030 TAM for LPKF process solutions

04
ENGAGED WITH TIER-1 CUSTOMERS FOR RAMP-UP

First capacity-expansion order placed in Q1 2026 and further ramp-up orders in negotiation

>70%

of Advanced Packaging customers have selected LPKF

05
POSITIONED FOR GROWTH ON A SCALABLE MODEL

North Star Wave 1 delivered; capex-light assembly scales with orders; no advanced packaging volume in FY2026 guidance

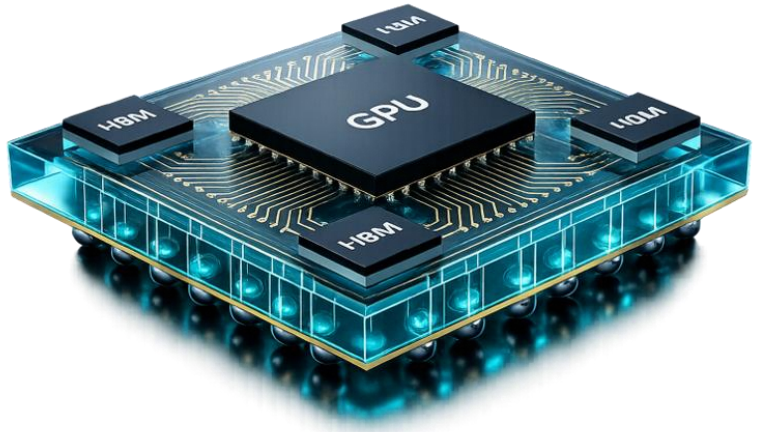
2028

double-digit EBIT margin targeted

AN ESTABLISHED SUPPLIER TO MULTIPLE INDUSTRIES

Fifty years supplying production laser systems across four industries — and now advanced packaging

1976	**Development**	Circuit-board prototyping	#1 worldwide
1993	**Electronics**	Depaneling and SMT stencils	#1 ex-China
2000	**Solar**	Thin-film scribing	#1 worldwide
2007	**Welding**	Laser plastic joining	Top-3
2019	**Glass — LIDE**	Development started for glass vias for AI	Pioneer and market leader with global track record



50 years	**60+** countries	**17.7%** into R&D

LPKF has taken fifty years of laser process expertise into AI advanced packaging — and now provides the process solutions for a market of EUR 1.7bn by 2030 only for the critical process step that LPKF serves

LPKF PRODUCT OFFERING

The [EUR 1.7bn] 2030 market is priced on two systems already available for sale — NEXAR LIDE structuring and NEXAR Ablate ABF ablation

FOCUS AREA

Advanced AI Packaging

Initial systems already shipping; production ramps announced with first clients

NEXAR LIDE 5000
Structuring · through-glass vias

NEXAR Ablate 5000
Singulation · RDL removal

NEXAR Bond 5000
Bonding · glass stacks

EUR 1.7bn 2030 Equipment TAM — LIDE structuring and Ablate ABF ablation only

TODAY'S CORE BUSINESS

Development

Circuit-board prototyping in hours, not days

EUR 27m
FY25 revenue · 24% of group

#1 worldwide
rapid PCB prototyping

Entered 1976 — the founding business

Electronics

Depaneling boards and cutting SMT stencils

EUR 36m
FY25 revenue · 31% of group

#1 ex-China
laser depaneling and stencils

Entered 1993 — largest segment today

Solar

Thin-film scribing at gigawatt line speed

EUR 28m
FY25 revenue · 25% of group

#1 worldwide
thin-film scribing

Entered 2007 — perovskite is the next wave

Welding

Joining plastics with light, not glue

EUR 24m
FY25 revenue · 21% of group

Top-3
worldwide in laser plastic welding

Entered 2000 — medical and robotics

LPKF's disclosed advanced packaging TAM of EUR 1.7bn counts structuring and singulation process steps only

Sources: LPKF FY2025 segment reporting.

WHY AI ADVANCED PACKAGING IS MOVING TO GLASS SUBSTRATES

LPKF OWNS THE ENABLING PROCESS FOR THE SHIFT TO GLASS

1. **AI is changing advanced packaging and moving it to glass substrates**

   600 TWh
   AI data centre energy consumption in 2026, of which c.16% is substrate-induced loss[1]

2. **Existing substrates are reaching their physical limits and glass is becoming a critical technology**

   30-80%
   Range of investor estimates for the glass share of substrates in 2030

3. **The EUR 1.7bn TAM is only one element of the opportunity and LPKF is targeting a far larger long-term opportunity**

   EUR 1.7bn[2]
   2030 machine TAM, flowing into a c.US$30bn advanced packaging solutions market[3]

4. **LPKF already leads the glass substrate value chain and that lead compounds rather than erodes**

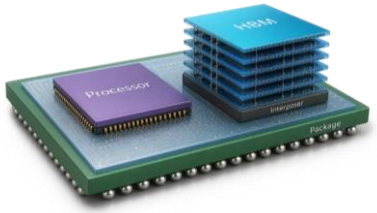
   >70%
   of advanced packaging customers worldwide have selected LPKF

Sources: [1]AI data centre energy consumption, IEA; [2]Based on information on wafer starts from Yole, Barclays, JP Morgan and Goldman Sachs; [3]High-End Performance Packaging 2025 Report, 2025, Yole Group.

AI IS FORCING A STRUCTURAL SHIFT IN CHIP PACKAGING…

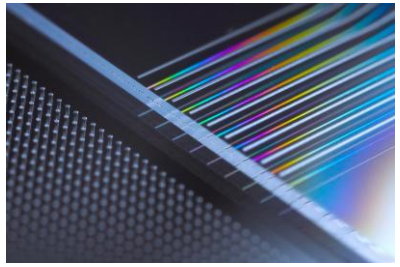
Compute now comes from how dies are assembled, not from shrinking the transistor

1 More compute per package/Tighter substrates

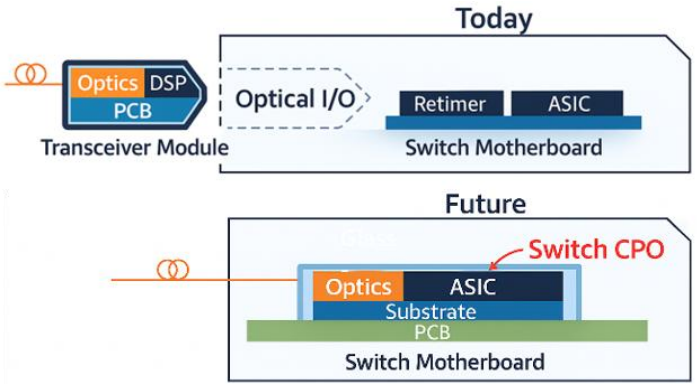


Laser Structuring with NEXAR LIDE 5000,
RDL Ablation with NEXAR Ablate 5000,
Laser Bonding with NEXAR Bond 5000.

2 Optics moves inside



Waveguide writing with NEXAR Write 5000 (on Roadmap)
and other process steps under evaluation

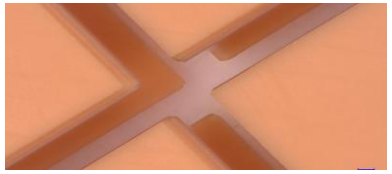


LPKF Solutions

SAME THREE SYSTEMS ENABLE SHIFTS 1 AND 2

NEXAR LIDE

Structuring · through-glass vias

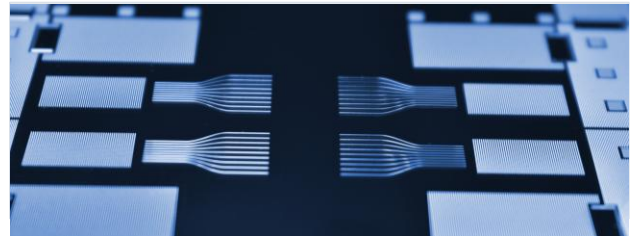


NEXAR Ablate

RDL removal · glass core singulation

NEXAR Bond

Adhesive-free glass-to-glass bonding



NEXAR Write

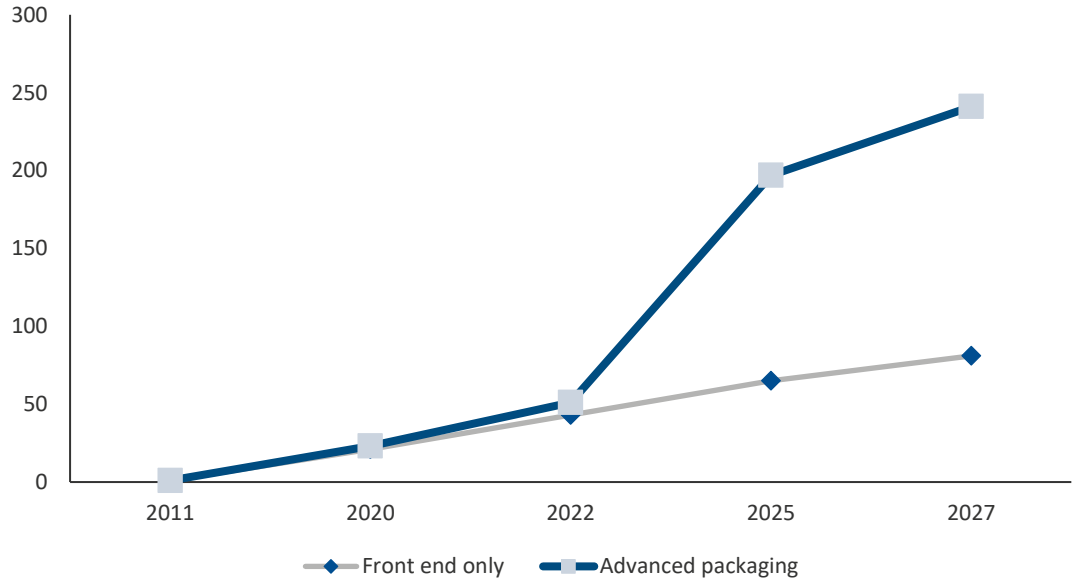
3D optical waveguides written inside the glass

Every one of these shifts needs a substrate that legacy organics cannot deliver
More process steps per package means more process equipment per package — which is what LPKF sells

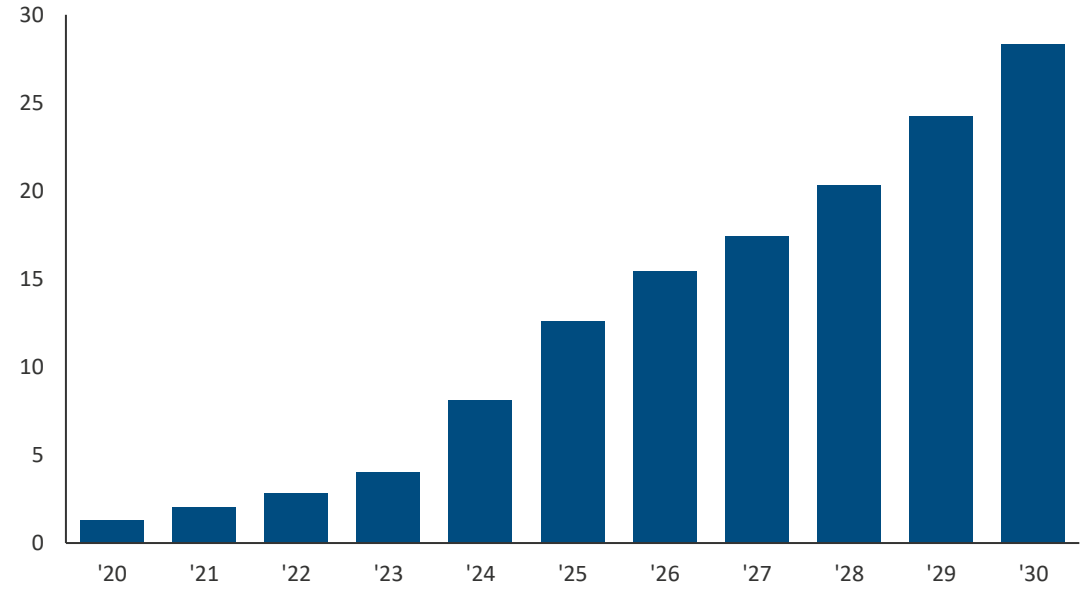
…WITH THE PACKAGING MARKET REVISED UPWARDS

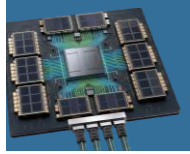
Compute gains now come from packaging

COMPUTE PERFORMANCE, INDEXED TO 2011 (SPEED x DENSITY)[1]



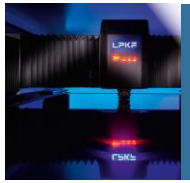
HIGH-END PERFORMANCE PACKAGING REVENUE (US$bn)[2]





c.250x

compute from advanced packaging since 2011, against c.80x from the front end alone



c.US$ 30bn

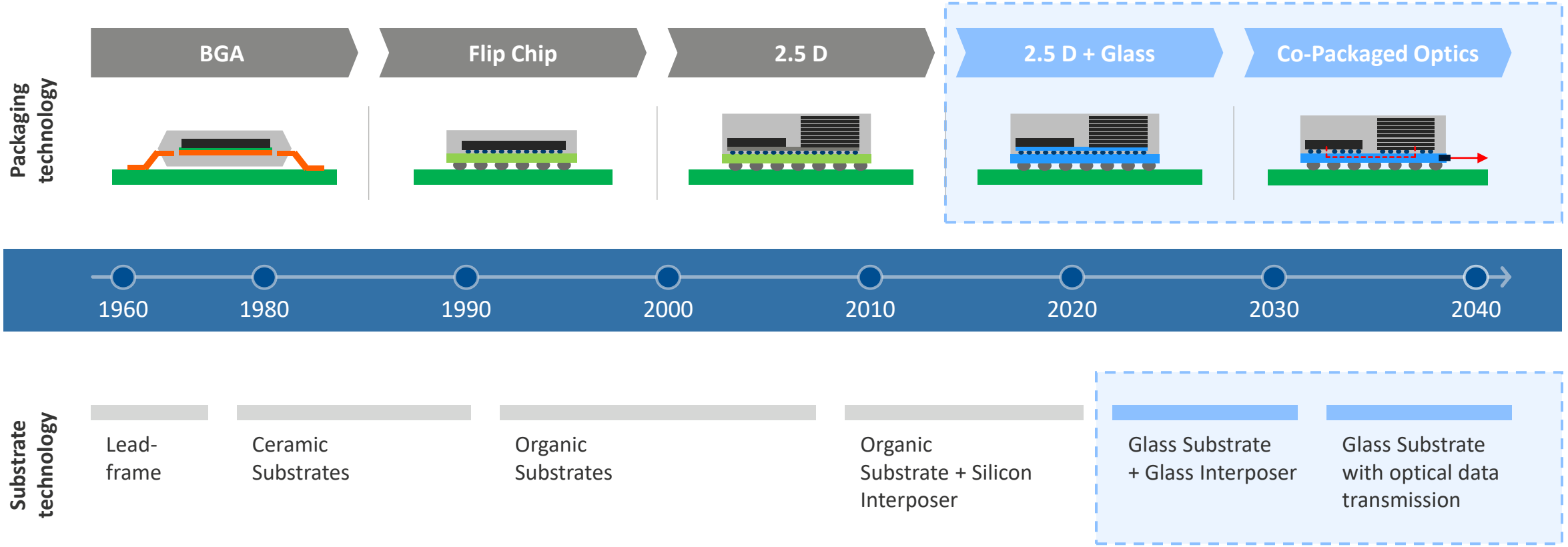
high-end packaging revenue by 2030, more than double the 2025 level

LPKF sells the equipment this spending buys. Glass adds three new process steps to every package — and two of the three are LPKF's

Sources: [1]TSMC. [2]High-End Performance Packaging 2025 Report, 2025, Yole Group.

2 EXISTING SUBSTRATES ARE REACHING THEIR LIMITS…

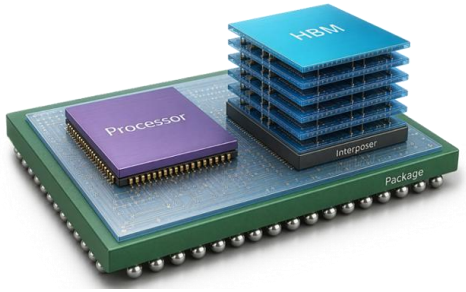
Every substrate generation has been replaced when it stopped scaling — organic is at that point now



Each transition took roughly a decade and reset the equipment base. Glass is positioned to be the high-volume substrate of choice for AI advanced packaging

2 …BREAKING ON SIZE, SPEED AND COST…

Three separate physical limits, all reached at once — and glass is the only material that answers all three



SIZE

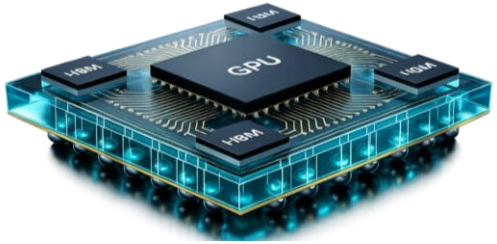
Reticle-scale

AI packages are now reticle-scale and larger. Organic warps as area grows — flatness, not wiring, sets the yield limit

SPEED

c.16%

of AI data centre power is lost in the substrate — close to 100 TWh a year of the c.600 TWh AI data centres consume in 2026. Glass delivers the signal integrity AI data rates require, worth c.EUR 4.8bn of energy savings[1]



COST

Costly at large area

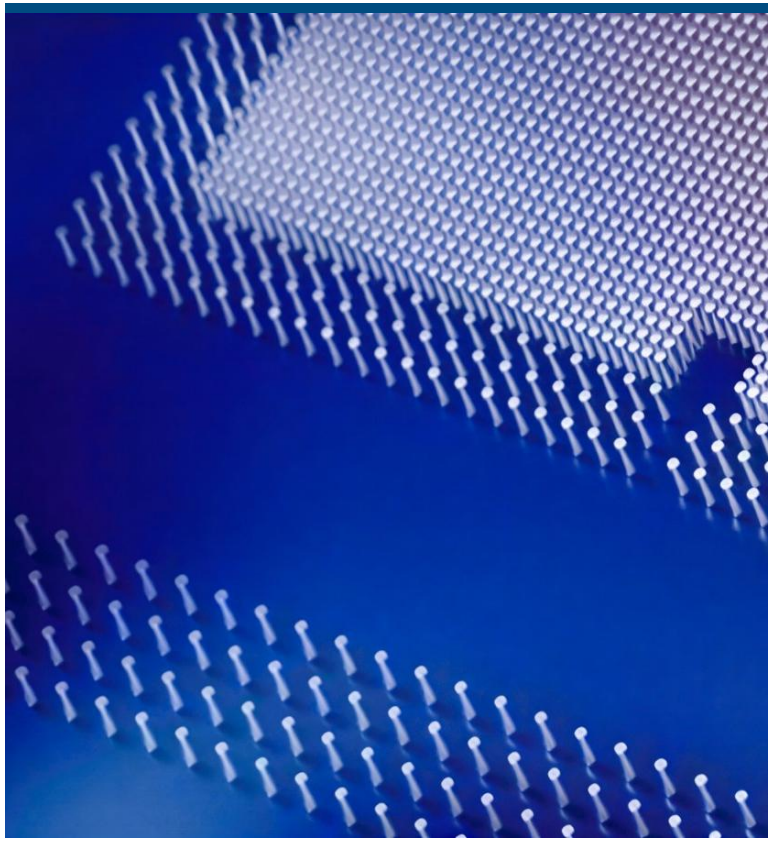
Silicon interposers perform well electrically and remain the choice at small format; glass adds significant cost advantages at panel scale

None of the three can be fixed incrementally – which is why the industry is changing material, not specification

Sources: [1]IEA.

2 …ENABLING GLASS TO BECOME THE CRITICAL TECHNOLOGY

Same three constraints, answered by one material change



ORGANIC TODAY	GLASS
PACKAGE SIZE	
Warps as area grows — flatness, not wiring, sets the yield limit	**Near-zero warpage** Panel-level processing to 600 x 600 mm with flatness under 2 µm
BANDWIDTH	
Electrical bandwidth is limited and energy-intensive	**1:50 via aspect ratio** Dielectric constant 4–6 against silicon's 12; supports 2/2 µm line and space RDL
ENERGY	
c.16% of datacentre power is lost in the substrate	**EUR 4.8bn saving potential** CTE matched to silicon at 3.2–3.5 ppm/°C; microfluidic channels enable in-package liquid cooling

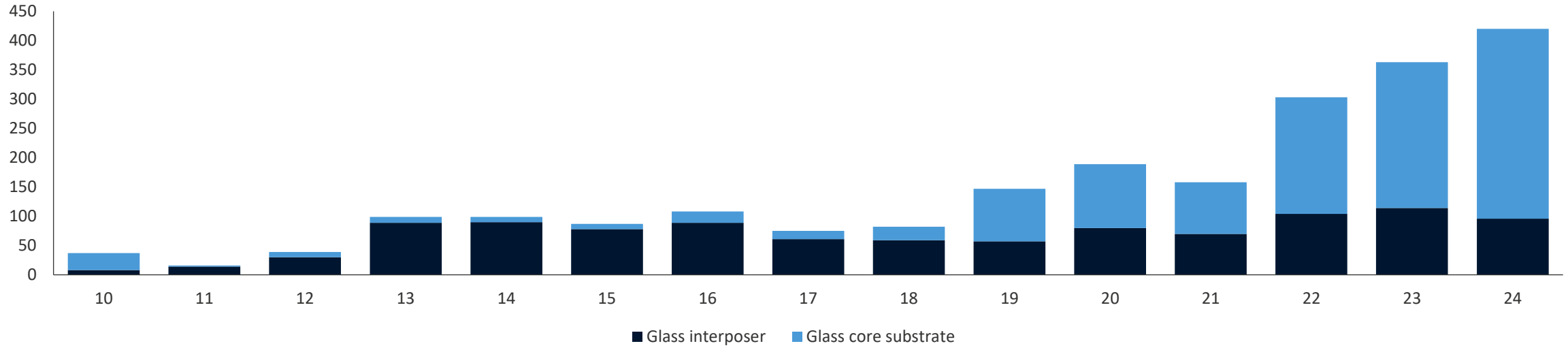
Glass answers all three at once and replaces a costly large-area silicon interposer while doing it

Sources: AI data centre energy consumption, IEA; substrate-induced share of data centre power, EUR 4.8bn saving potential and glass performance data, LPKF.

2 THE INDUSTRY HAS ALREADY COMMITTED…

Patent filings to 2024 — the 2025 number is not yet available — and the names filing are the largest packaging players in the industry

GLASS SUBSTRATE PATENT PUBLICATIONS (NEW APPLICATIONS PER YEAR)[1]



WHO IS FILING ON GLASS INTERPOSERS

tsmc, intel, SAMSUNG, Amkor Technology, IBM

WHO IS FILING ON GLASS CORE SUBSTRATES

intel, absolics, LG, SAMSUNG, Apple

Patent filings multiplied between 2018 and 2024, and the filers are the industry's established packaging players — the R&D is being spent by the companies that will build the capacity

Sources: [1]2025 number is not yet available.

2 ...WITH RECENT ANNOUNCEMENTS FROM MAJOR PLAYERS

2 July 2026

SEOUL ECONOMIC DAILY

Samsung Electro-Mechanics Sets Up Glass Substrate JV "GLASEM", Targets 2030 Mass Production

Samsung Electro-Mechanics (009150.KS) is moving to seize an early lead in glass substrates, an innovative packaging material for artificial intelligence (AI) chips. The company plans to elevate the related technology to a mature level by 2030, establish a mass production system, and secure a leading position in a next-generation growth area. Samsung Electro-Mechanics said Tuesday it has signed a definitive agreement to establish a joint venture (JV) called "GLASEM" (tentative name) with Dongwoo Fine-Chem, a wholly owned Korean subsidiary of Japan's Sumitomo Chemical Group, to produce "glass core," a key material for glass substrates.

16 December 2025

TOPPAN INC.

TOPPAN to Install Pilot Line for Advanced Semiconductor Packaging at Ishikawa Plant

Tokyo – December 16, 2025 – TOPPAN Inc. (TOPPAN), a TOPPAN Group company and wholly owned subsidiary of TOPPAN Holdings Inc. (TYO: 7911), will install a pilot line to conduct research and development of advanced semiconductor packaging at the Ishikawa Plant (Nomi, Ishikawa Prefecture, Japan) acquired in 2023, aiming to commission the line in July 2026. Organic redistribution layer (RDL) interposer development to be conducted on the pilot line has been selected for the Research and Development Project of the Enhanced Infrastructures for Post-5G Information and Communication Systems/Development of Manufacturing Technologies for Industrial Technology Development Organization ...

22 January 2026

TECHPOWERUP

Intel Unveils Glass Core Substrate with EMIB Multi-Chip

At NEPCON Japan 2026, Intel showcased its latest glass substrate technology designed to power the next generation of advanced AI and HPC accelerators. According to SemiVision Taiwan, which shared one of the slides, Intel has developed a new high-performance core glass substrate measuring 78x77 mm for the entire package. This substrate can accommodate approximately twice the reticle size with silicon, equating to about 1,716 mm^2 (2x858 mm^2) of silicon area for logic and memory. It is the first 10-2-10-thick glass core substrate featuring Intel's EMIB multi-chip module technology. This configuration includes 10 redistribution layer (RDL) build-up layers on the top of the substrate, which are used to redistribute signals from the die.

3 February 2026

NEWS

Samsung Reportedly Shifts Glass Substrate Project to Business Unit, Eyes 2027 Ramp-Up

As chip heavyweights such as Intel accelerate their push into glass substrates, Samsung is also edging closer to commercialization. According to ETNews, Samsung Electro-Mechanics has begun gearing up for market entry, with the project reportedly shifting from an advanced R&D unit to a business-focused execution team – signaling a move from development to market deployment. The report notes that Samsung expects the glass substrate era to enter full swing from 2027 onward. It is currently developing glass substrate samples with customers, including global semiconductor companies, as per ETNews. From Materials to Manufacturing: Samsung's Full Glass Substrate Push

8 April 2026

NEWS

Apple Reportedly Sources Glass Substrate Samples Directly, Signaling Further In-House AI Server Chip Push

Apple may be moving to bring AI server chip development further in house, as recent developments suggest. According to Wccftech, citing The Elec, sources say Samsung Electro-Mechanics has supplied semiconductor glass substrate samples to Apple. Following earlier sample shipments to custom AI chip designer Broadcom, the company is now expanding its potential customer base to include Apple. As the report adds, Apple is collaborating with Broadcom on AI server chips, with the internally codenamed 'Baltra' expected to be manufactured using TSMC's 3nm N3E process. Broadcom, meanwhile, remains the largest potential customer for Samsung Electro-Mechanics' glass substrate ...

19 May 2026

IC & PCB UNION

SKC Raises KRW 1.17 Trillion to Accelerate Glass Substrate Commercialization

South Korean advanced materials company SKC (KRX: 011790) said on May 12 that it finalized the price for its rights offering at KRW 99,500 per share, raising about KRW 1.1671 trillion (USD 775.8 million/CNY 5.28 billion). The company will issue 11.73 million new shares. The final amount rose by around KRW 340 billion (USD 226 million/CNY 1.54 billion) from the initial plan due to a stronger-than-expected share price rally. SKC said on May 17 that the offering was oversubscribed, with demand driven by expectations for its semiconductor glass substrate business and balance sheet restructuring. Existing shareholders subscribed to 113.01% of the offering, with ....

19 May 2026

IC & PCB UNION

Taesung Wins Glass Substrate Equipment Order Marking Entry Into AI Packaging Market

South Korean PCB wet-process equipment maker Taesung Co., Ltd. (KOSDAQ: 323280) said on May 18 that it has secured an order for key glass substrate process equipment from a leading South Korean electronics components company, marking its official entry into the AI semiconductor packaging equipment market. The order covers pre-treatment and etching (wet-etch) systems to be deployed in the customer's next-generation glass substrate R&D line and pilot production facility. The company said the equipment is particularly critical for Through Glass Via (TGV) processes, one of the most technically challenging steps in glass substrate .....

21 May 2026

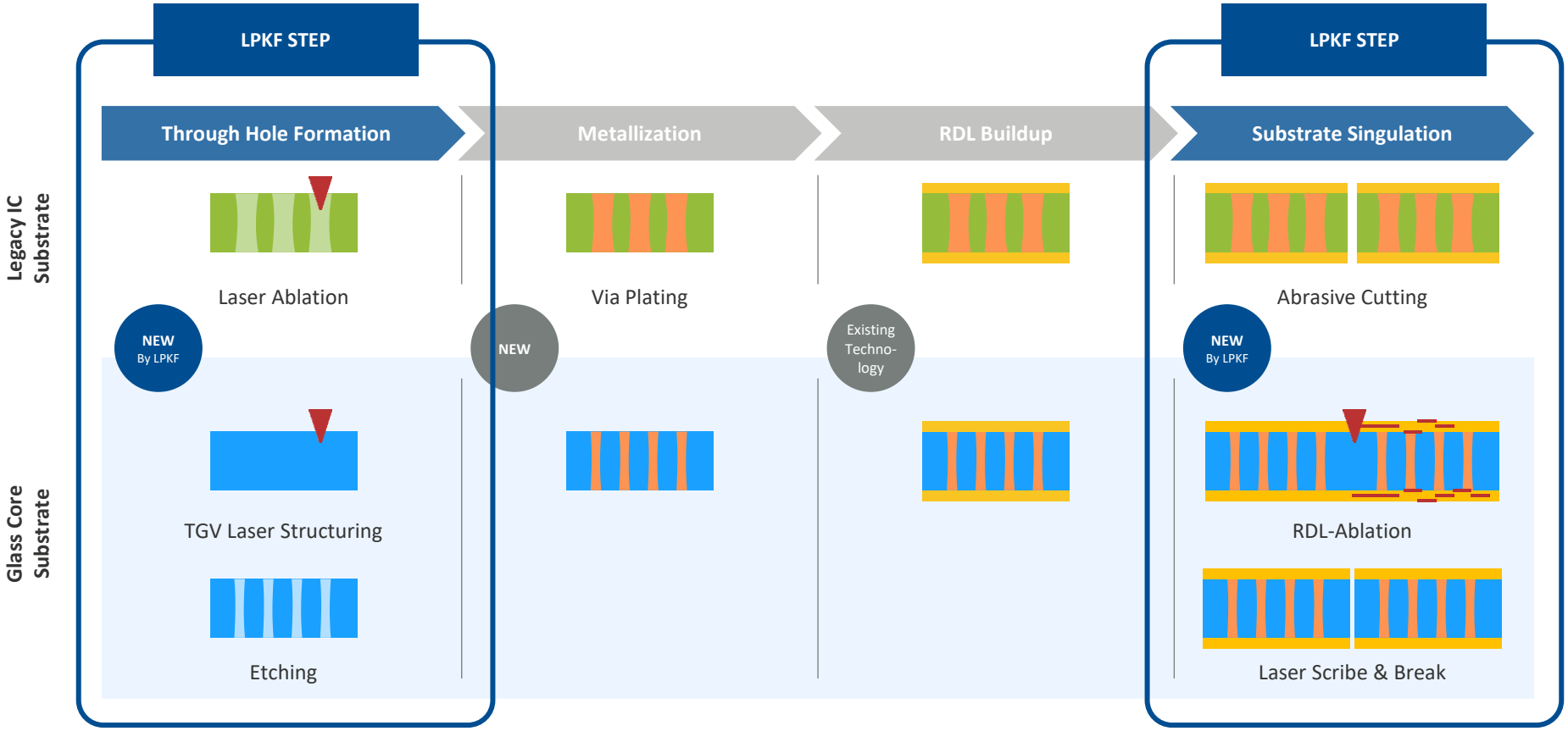
AD HOC NEWS

Glass core substrates from TSMC for next-gen AI chips

Glass core substrates from TSMC aim to replace organic chip packaging in high-performance AI and HPC processors, promising higher density and better power use for future data centers in the US and worldwide. Glass core substrates from TSMC are emerging as a next-generation packaging platform for high-performance processors, especially AI accelerators and HPC chips used in large data centers. Glass core substrates from TSMC are designed to improve routing density and thermal stability compared with conventional organic substrates, a shift highlighted by industry analysis on advanced chip packaging for AI workloads 3D InCites, August 2025.

2 LPKF SUPPLIES TWO OF THE THREE NEW PROCESS STEPS

A glass core line needs three new process steps that a legacy line does not have



2 of 3

new process steps in a glass core line are LPKF's — through-glass via formation and substrate singulation

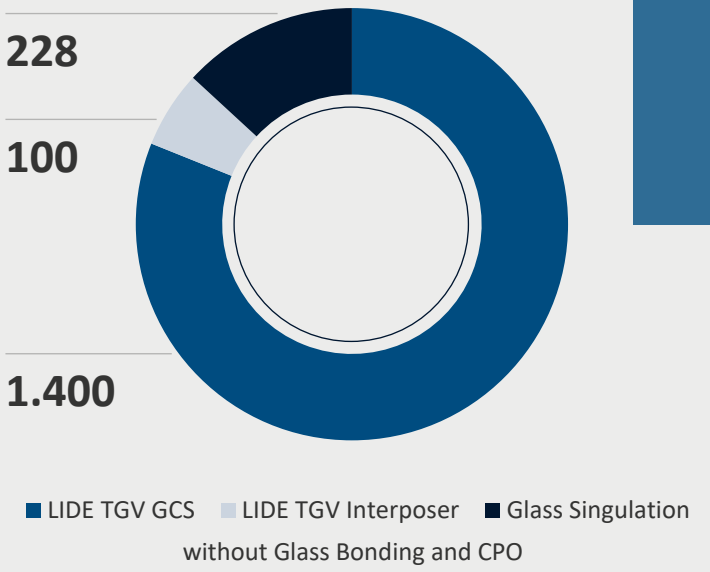
Applications under evaluation for bonding: thick substrates and active cooling

More than 70% of advanced packaging tool selections in pre-production (phase 1) have gone to LPKF

3 TAM FOR LIDE SOLUTIONS EXPANDS SIGNIFICANTLY WITH THE ACCELERATION OF AI…

AI-driven growth in HPC materially broadens the addressable market for LIDE solutions

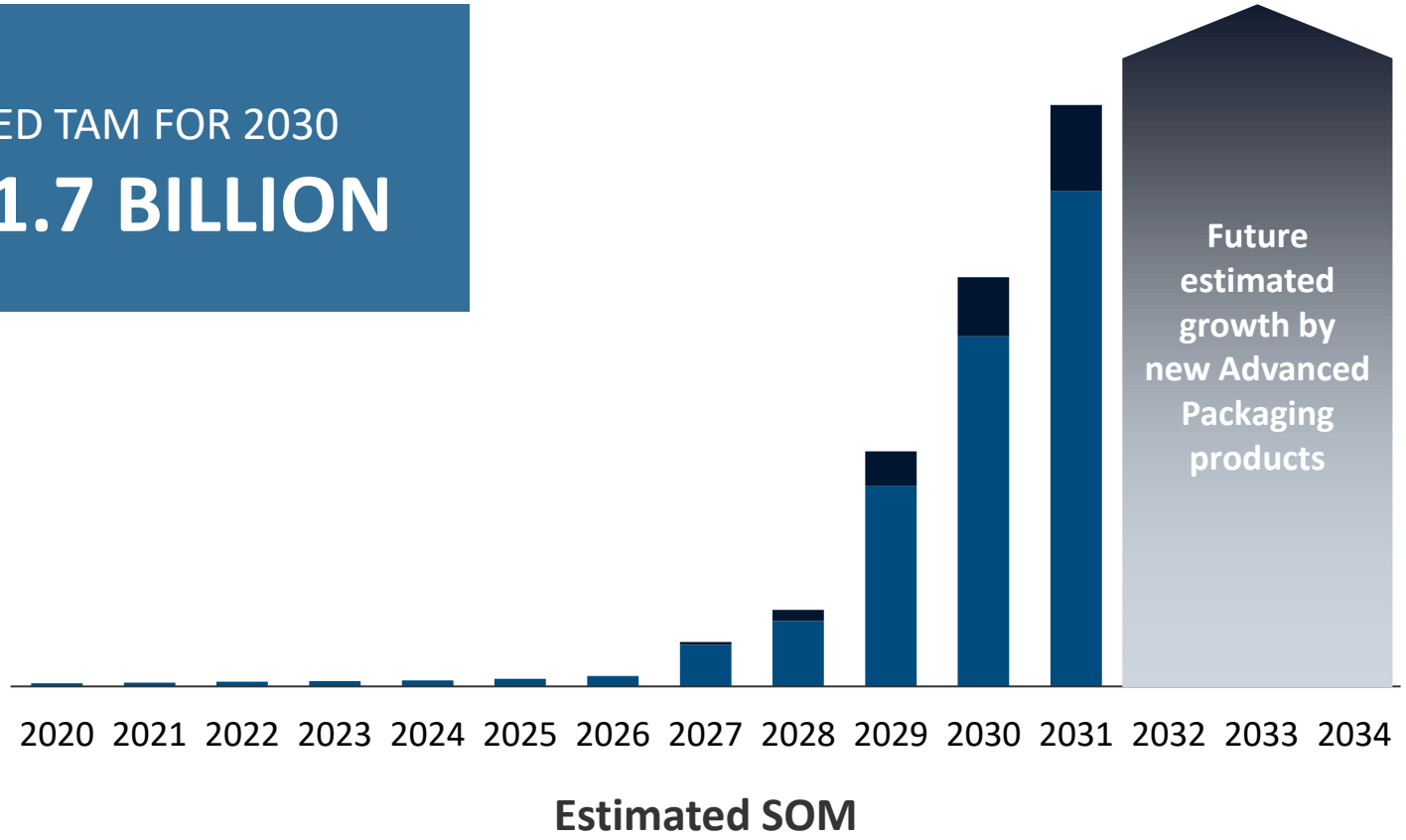
In million EUR



Based on information on wafer starts from Yole, Barclays, JP Morgan and Goldman Sachs

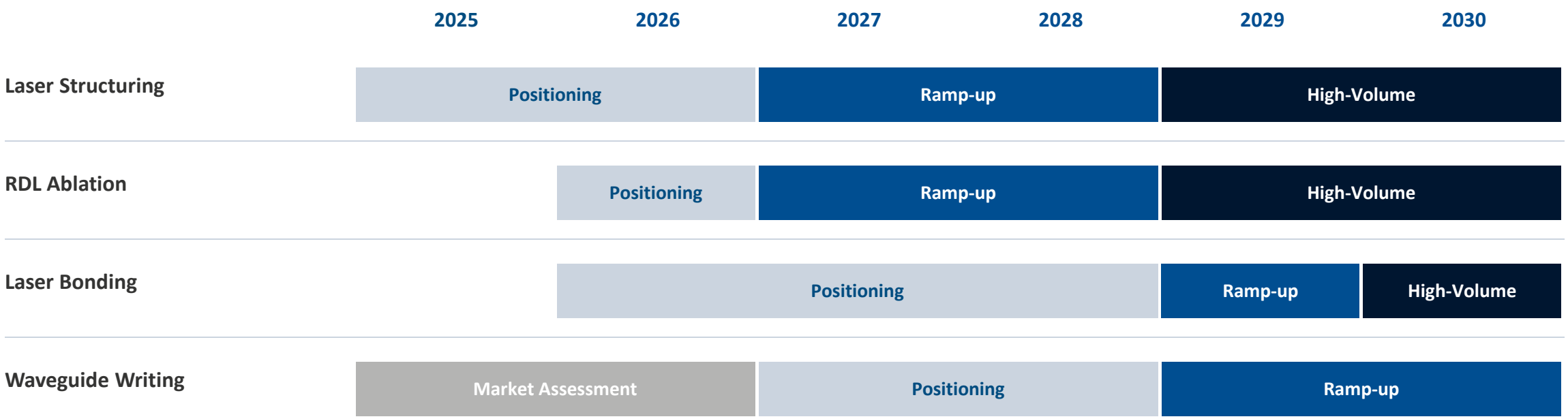
ESTIMATED TAM FOR 2030

EUR 1.7 BILLION



3 … AND LPKF IS POSITIONED TO SUPPLY A VERY LARGE MARKET OPPORTUNITY

Four products on the roadmap, three already commercial — each on a dated path to high volume



3 of 4 processes
available for sale to customers today

10x+ the markets it serves
after the Q1 2026 portfolio expansion

2027
Ramp-up year begins

Three of the four processes are available for sale to customers today. Co-packaged optics is still in market assessment

4 LPKF ALREADY LEADS THE GLASS SUBSTRATE VALUE CHAIN…

A dominating win rate across every key customer engagement, excluding local Chinese players

OEM

aws (USA) · intel (USA) · SAMSUNG (KOR) · Google (USA) · NVIDIA (USA)

(USA) · AMD (USA) · BROADCOM (USA) · tsmc (TWN) · HUAWEI (CHN)

IC SUBSTRATE BUILT-UP

- Player 1 (KOR)
- Player 2 (EU)
- Player 3 (USA)
- Player 4 (USA)
- Player 5 (KOR)
- Player 6 (TWN)
- Player 14 (JPN)
- Player 15 (JPN)
- Player 16 (CHN)
- Player 17 (JPN)
- Player 18 (JPN)

TGV & METALISATION

- Player 7 (KOR)
- Player 8 (KOR)
- Player 9 (KOR)
- Player 10 (KOR)
- Player 11 (KOR)
- Player 12 (KOR)
- Player 13 (CHN)

EQUIPMENT

LPKF

- Philoptics (KOR)
- local manufacturers (CHN)
- Trumpf (GER, laser technology)
- E&R (TWN)

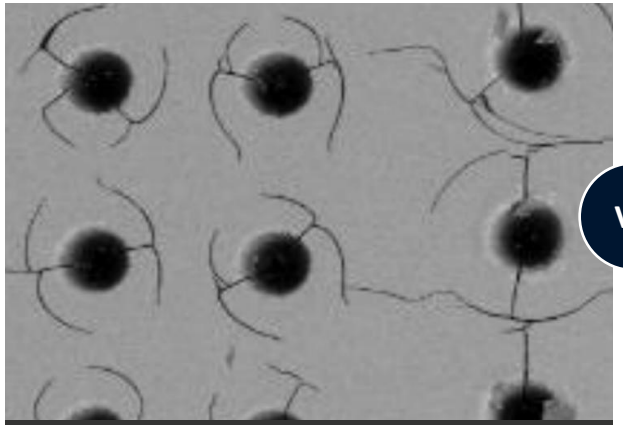
Across the TGV and metallisation layer the customers that matter are already on LPKF tools, or working from LPKF samples — the qualification decisions are largely made

- Uses LPKF tool
- Works with LPKF samples, no tool yet
- Works with LPKF samples but different tool

4 ...A LEAD THAT COMPOUNDS RATHER THAN ERODES

Process maturity, market leadership and process-level IP give LPKF an unmatched position

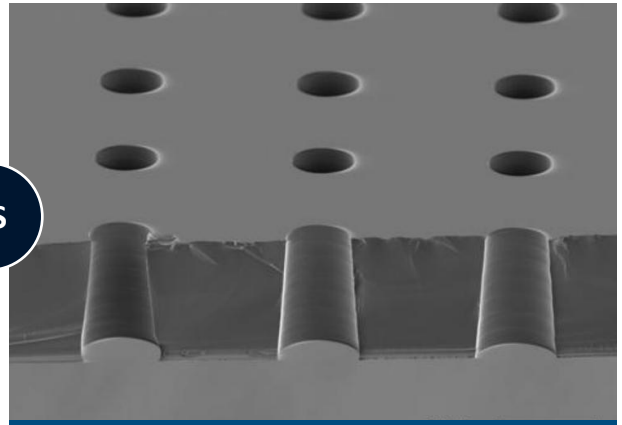
THE PROCESS IS THE TECHNOLOGY, AND IT IS VISIBLE IN THE GLASS



CONVENTIONAL, SINGLE PASS

Thermal stress cracks the glass — chipping, debris, low yield

VS



LIDE, TWO STEP

Laser modification then etching — defect-free vias, 1:50 aspect ratio

1:50 via aspect ratio at production throughput — the only cost-effective process for defect-free glass microstructures

8 years of field operation and accumulated process data

Dominating market share in prototyping lines

Process-level patent effective September 2025, with rights confirmed in Europe and Korea

A competitor can buy a laser. What they cannot buy is eight years of process data and the customers who already qualified on it

4 IT IS PROTECTED AND QUALIFIED…

A patent on the process itself, a multi-year qualification cycle, and LPKF's own glass foundry

PATENTED

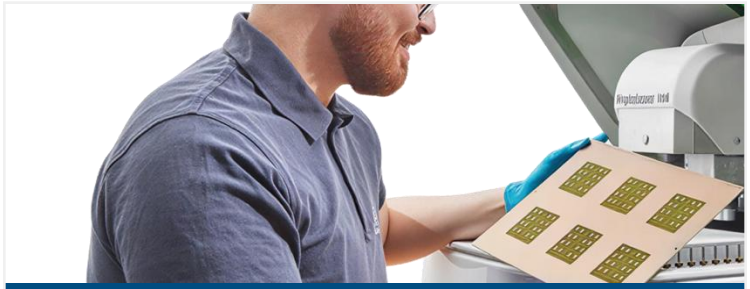
The process, not the tool

- Core LIDE process patent — the most valuable in the portfolio; filed in Europe 2022, EPO confirmed validity March 2025
- Korean patent effective 1 September 2025
- Covers the processing methodology itself, not the tool
- Enforcement proceedings under way in China

QUALIFIED

Multi-year R&D and qualification effort

- Customers qualify for several years before volume
- Process expansions were customer-requested
- Eight years of field operation behind the data



OPERATED IN-HOUSE

LPKF's own glass foundry

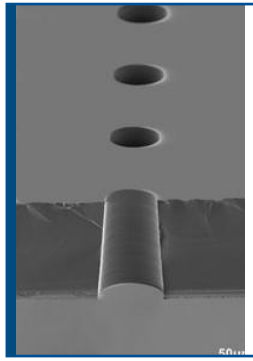
- Vitrion runs customer glass on its own LIDE systems
- Process knowledge a pure equipment vendor cannot reach
- Feeds every improvement straight back into the tools

The core LIDE process patent is the most valuable asset in the portfolio — it covers the process, not the machine, so a competitor cannot design around it by building a different laser

4 …ON ONE PLATFORM THAT SCALES FROM PILOT TO VOLUME

Process parameters developed at R&D transfer straight into production — only the automation level changes

THREE PROCESS FAMILIES

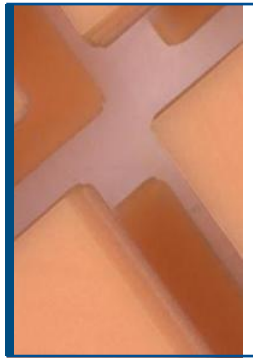


NEXAR LIDE

Forms the vias

5 µm via diameter, aspect ratios to 1:50

NG rate below 5 ppm at production yield

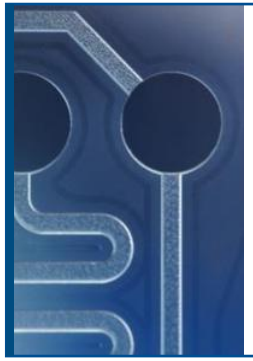


NEXAR ABLATE

Removes the RDL

Zero SeWaRe initiation, confirmed by cross-section

Inline inspection on every substrate



NEXAR BOND

Bonds glass to glass

Up to 250 mm/s, 50 µm seam width

Room temperature, >90% uptime

ONE PLATFORM, THREE SCALE-UP STAGES — THE PROCESS DOES NOT CHANGE, ONLY THE AUTOMATION

M — **Manual loading, wafer and panel**

R&D, technology evaluation and pilot production

S — **Automated wafer handling with EFEM**

Wafer production in a semiconductor fab

P — **Full panel automation, 515 x 510 mm**

24/7 high-volume manufacturing

A customer qualifies once on an M system, then scales to S and P without requalifying
Every ramp is LPKF revenue — and switching vendor means restarting a multi-year qualification

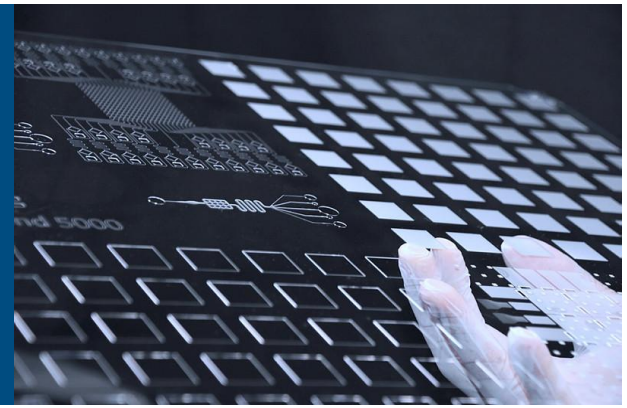
4 KEY CUSTOMER WIN

A customer that already runs LPKF equipment has selected the Company for its first production ramp

ANNOUNCEMENT

Leading Asian advanced semiconductor packaging manufacturer selects LPKF's glass processing equipment for production ramp-up

Corporate News — 23 September 2026



WHAT WAS ORDERED

- Letter of intent for NEXAR LIDE systems
- Mid-single-digit million euro volume
- Firm orders expected shortly

WHY IT MATTERS

- Customer already operates an LPKF system and has fully qualified LIDE
- For the customer's first glass substrate production facility
- LPKF estimates its glass processing TAM at c.EUR 1.7bn by 2030

WHAT COMES NEXT

- LPKF expects the project to be followed by additional orders
- Reviewing options to strengthen global presence and capability
- Financing alternatives under evaluation, including a potential equity raise

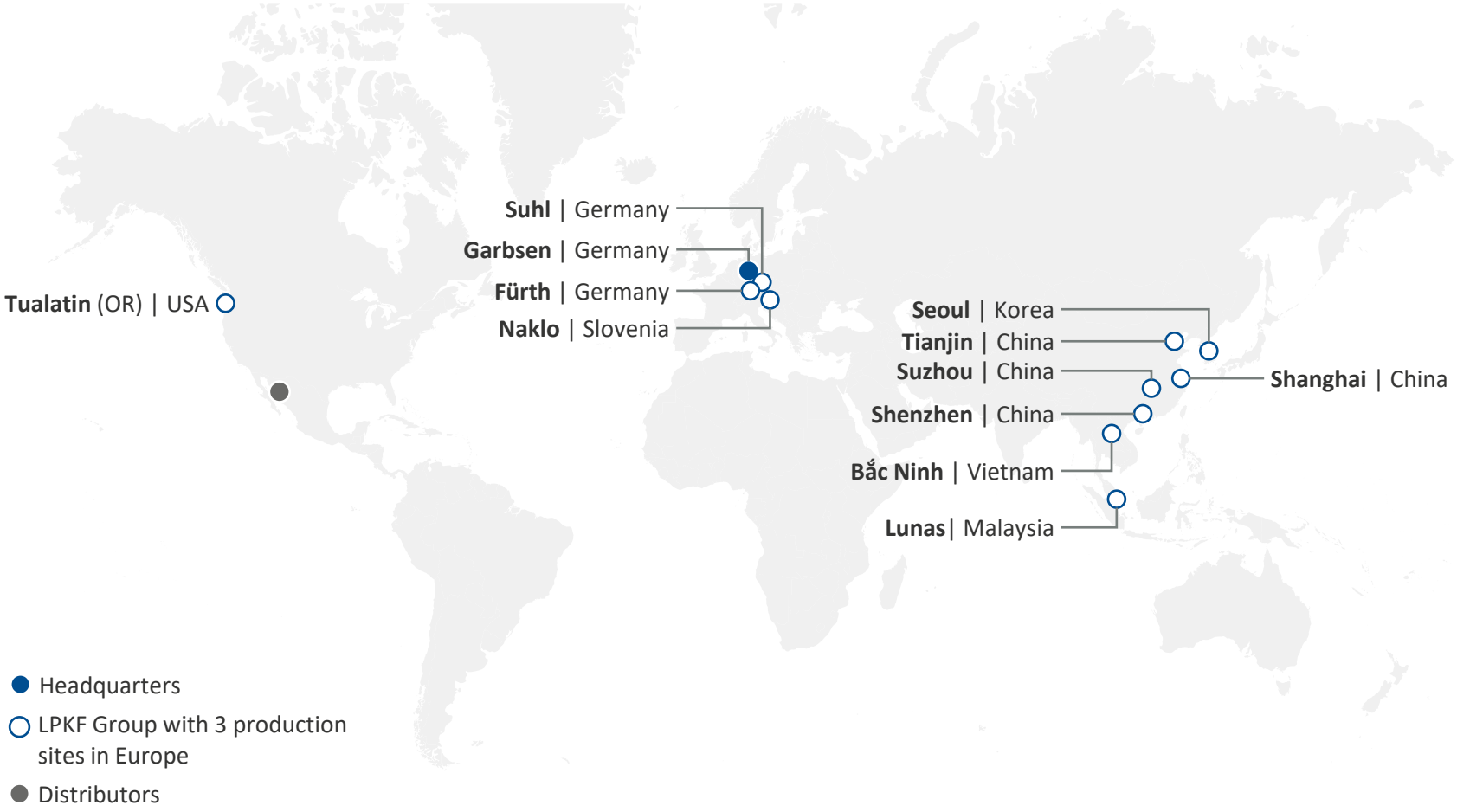
"We are positioning LPKF as a pivotal enabler of advanced packaging and next-generation AI. We expect this project to be followed by additional orders and to firmly anchor LPKF in the global supply chain for glass-based semiconductor packaging."
Klaus Fiedler, Chief Executive Officer, LPKF Laser & Electronics SE

Qualification has converted into capacity, with the first customer moving from a qualified LIDE process to a glass substrate production line
Mid-single-digit million euros today, with additional orders expected as the facility ramps

OPERATIONS AND SCALE-OUT

LPKF MANUFACTURING FOOTPRINT

Fürth production closed and Suhl ramped — the footprint was consolidated before the ramp, not during it



Global Footprint

Active in 60 + countries
8 subsidiaries in Europe, Asia and North America

Flexibility

Capex-light manufacturing platform designed for fast ramp-up in new locations

Security

50 years of experience delivering dependable supply where LPKF customers need it

LPKF ALREADY HAS THE INFRASTRUCTURE TO SCALE

Capex-light assembly, production reconfigured ahead of the ramp, LPKF's own glass foundry and service where LPKF customers build

Capex-light assembly

LPKF integrates lasers and optics rather than running a fab, so output scales without heavy capital.

Production already reconfigured

The new Suhl production setup was delivered under North Star Wave 1 — ahead of the ramp, not after it.

LPKF's own glass foundry

LPKF runs customer glass on its own LIDE systems, proving volume before a customer commits to capacity.

Service wherever the fabs are

8 subsidiaries and 50+ distributors support the installed base in over 60 countries — service wherever the fabs are

3
production sites in Europe

8
subsidiaries worldwide

664
employees, down from 732

62.8%
equity ratio at H1 2026

The first capacity-expansion order was already placed in Q1 2026 — capacity can be added without a fab, and the balance sheet funds the ramp

CURRENT FINANCIAL UPDATE

Proprietary & Confidential

REVISED 2026 GUIDANCE AND MID-TERM ASPIRATION

ACTUALS 2025

Revenue:
EUR 115.3 million

Adjusted EBIT margin:
0%

REVISED GUIDANCE FY 2026

Revenue
EUR 93 – 100 million

(prev: EUR 105 – 120 million)

Adjusted EBIT margin[1]
between -7.0% and -2.5%

(prev: -3.0% and +4.5%)

MID-TERM ASPIRATION

The Management Board aims to achieve a sustainable double-digit EBIT margin for the group by 2028

- **Semiconductor Market:** Strong strategic positioning with LIDE technology and expanded product portfolio offering substantial growth potential
- **SMT and Rapid PCB Prototyping:** Solid growth prospects
- **Solar:** Despite current weakness, the transition to perovskite technology is seen as a promising growth opportunity
- **Welding:** Strategic realignment expected to yield long-term profitable growth
- **Overall:** Structural adjustments are crucial to ensure LPKF's resilience and competitiveness, as no significant short-term growth impulses are expected amidst economic uncertainty

[1] Adjusted EBIT is calculated by excluding restructuring and severance costs, effects from changes in the scope of consolidation, and adjustments to the Long-Term Incentive (LTI) resulting from fluctuations in the performance factor or the share price. For the 2026 fiscal year, LPKF expects exceptionally high restructuring costs of approximately 3 – 4% of revenue as part of the North Star transformation program.

NORTH STAR UPDATE

North Star was structured in **Wave 1** and **Wave 2** with the overall target to reach double digit EBIT
Wave 1: Urgent, fast track cost savings
Wave 2: LPKF fundamentals, improvement in efficiency focus on operational processes and product development excellence

Wave 1

Defined Measures completed

- ☑ Engineering Rightsizing
- ☑ New Production Suhl
- ☑ WQ Transformation
- ☑ Strategic Procurement Cost Reduction

Overall Headcount reduction in Wave 1 from 732 to 664

Wave 1 measures have been implemented, their effects have been realized

Wave 2

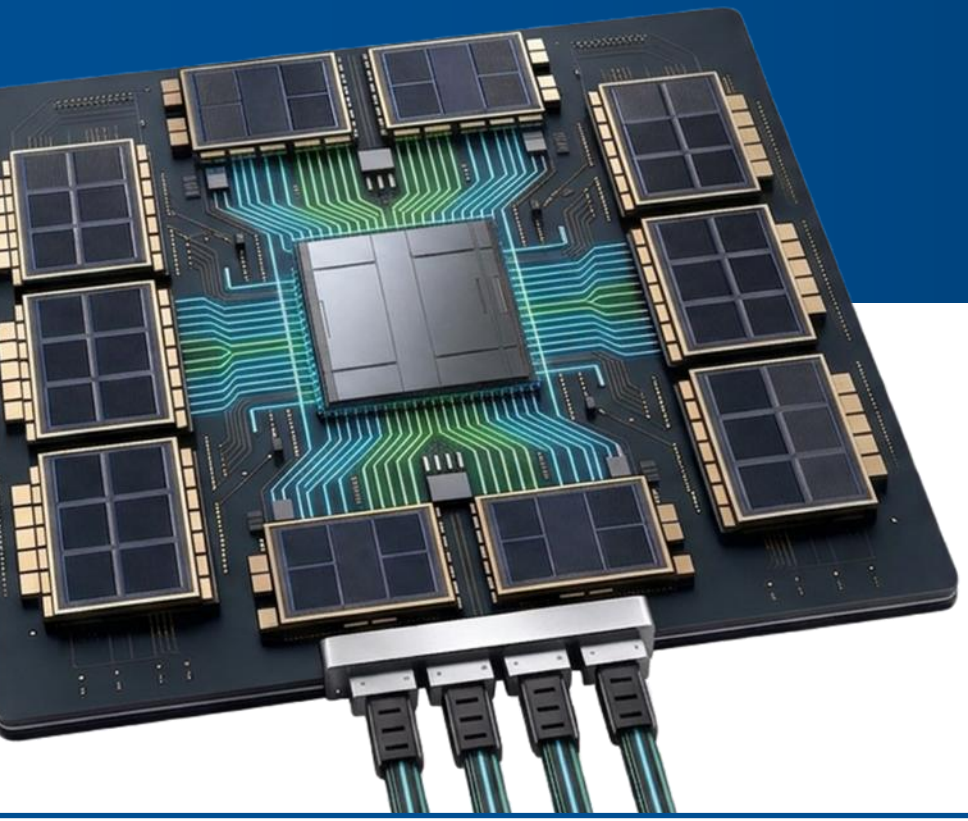
Transformation into Functional Organization

- Transitioning to a leaner, functionally led operating model
- Clarifying accountability and accelerating decision-making
- High class product development in innovation to the market
- Standardizing End-to-End processes to strengthen resilience, scalability
- Unlocking cross-functional synergies and structural efficiency gains

Wave 2 measures are planned, works council negotiations are ongoing
→ Further Headcount reduction in discussion

Support ramp up of Advanced Packaging based on high efficiency in processes

Double-digit EBIT margin by 2028, with the cost base already reset



PIONEERING

WITH A FOCUS ON LARGE VOLUME AI GROWTH MARKETS

- A pioneering spirit is in LPKF's genes. Through creativity, perseverance and a passion for innovation, LPKF has repeatedly opened up new markets and gained leading positions in laser processing solutions
- LPKF will continue to do so in the future with the focus now on far larger markets — glass-based advanced packaging, with a LIDE addressable market of approximately EUR 1.7bn by 2030
- Extending beyond glass structuring into substrate singulation, laser glass bonding and co-packaged optics on glass
- LPKF's aim is to be the first to implement the latest technological standards together with its customers

Appendix

CORE BUSINESS DEEP DIVE

DEVELOPMENT: MARKET LEADER WITH 50 YEARS OF EXPERIENCE

REVENUE

27,1 Mio.	2025
26,2 Mio.	2024
29,0 Mio.	2023

ADJ. EBIT

1,3 Mio.	2025
0,9 Mio.	2024
3,1 Mio.	2023

MARKET POSITION

#1

LOCATION

Garbsen
Germany

Naklo
Slovenia

MAIN MARKETS

Electronics
Medical
RF & Microwave
Defense

MARKET OFFERING

- Provides in-house solutions for Rapid PCB Prototyping, without wet chemistry
- Develops and sells mechanical and laser-based systems for R&D departments, universities and research institutes worldwide
- Offers inhouse laser processing of flex and ceramic materials
- Serves a fragmented global customer base through a long-standing international sales partner network
- Market leader in Rapid PCB Prototyping and continuously refines its portfolio

ELECTRONICS: SMT SOLUTIONS – RAISING PRODUCTIVITY AND QUALITY IN ELECTRONICS MANUFACTURING

REVENUE

35,9 Mio. 2025[1]
36,9 Mio. 2024[1]
32,7 Mio. 2023[1]

ADJ. EBIT

-2,6 Mio. 2025[1]
-0,9 Mio. 2024[1]
-2,3 Mio. 2023[1]

MARKET POSITION

#1 Laser Depaneling, Stencil (Outside China)

LOCATION

Garbsen
Germany

MAIN MARKETS

PCBA
SMT Stencil
…

MARKET OFFERING

Bundles laser solutions for series production of electronic modules, focusing on SMT processes in high-Volume Manufacturing.

Supplies CuttingMaster systems for precise, low-stress depaneling of PCBs, enabling highly automated smart-factory lines

Builds StencilLaser systems, including MicroCut-X, for high-precision solder paste and wafer stencils

Supports EMS, medical and automotive customers with application know-how, software and service for stable laser production

Notes: [1]Including figures from Advanced Packaging.

WELDING: CLEAN, PRECISE PLASTIC JOINING FOR HIGH-PERFORMANCE APPLICATIONS

REVENUE

24,0 Mio.	2025
18,6 Mio.	2024
23,1 Mio.	2023

ADJ. EBIT

0,5 Mio.	2025
-4,8 Mio.	2024
-0,8 Mio.	2023

MARKET POSITION

TOP3 Supplier

Technology leader

LOCATION

Fürth

Suhl

Germany

MAIN MARKETS

Medical

Automotive

Consumer Electronics

Smart Robotics

MARKET OFFERING

Provides turnkey laser plastic welding solutions for joining components precisely, cleanly and without additional chemicals or particles

Develops standardized stand-alone and integration systems as well as customized tools and solutions, including process monitoring and software for full quality control

Serves demanding applications in automotive supply, consumer electronics, medical technology and smart robotics worldwide with best-in-class process and polymer expertise

SOLAR: ENABLING NEXT-GENERATION THIN-FILM AND PEROVSKITE SOLAR MANUFACTURING

REVENUE

28,3 Mio.	2025
41,2 Mio.	2024
39,5 Mio.	2023

ADJ. EBIT

1,6 Mio.	2025
5,7 Mio.	2024
4,4 Mio.	2023

MARKET POSITION

#1

LOCATION

Suhl
Germany

MAIN MARKETS

Thin Film Solar
Building Integrated PV
Transportation
…

MARKET OFFERING

Develops and manufactures laser systems to structure thin-film solar cells on large glass substrates with high precision

Technology and market leader in laser scribing systems that boost cell efficiency and lower cost per watt

Advances laser processes for new cell generations such as perovskite technologies

Develops Laser Transfer Printing (LTP) solutions that digitally deposit functional pastes and inks, enabling high-precision, contactless printing for advanced glass applications

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